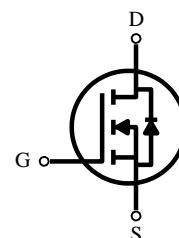
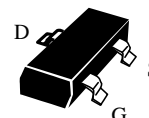


## N-Channel High Density Trench MOSFET

### Features:

- Super high dense cell trench design for low  $R_{DS(on)}$ .
- Rugged and reliable.
- Surface Mount package.

SOT-23



### PRODUCT SUMMARY

$V_{DSS}$	$I_D$	$R_{DS(on)}$ (m $\Omega$ ) Max
60V	2.8A	95 @ $V_{GS} = 10V$
	2.3A	115 @ $V_{GS} = 5V$
	2.1A	120 @ $V_{GS} = 4.5V$

### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous <sup>a</sup> @ $T_A = 25\text{ }^\circ\text{C}$ -Pulse <sup>b</sup>	$I_D$	2.8	A
	$I_{DM}$	10	A
Drain-Source Diode Forward Current <sup>a</sup>	$I_S$	1.2	A
Maximum Power Dissipation <sup>a</sup>	$P_D$	$T_A = 25\text{ }^\circ\text{C}$	1.25
		$T_A = 75\text{ }^\circ\text{C}$	0.75
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	- 55 to 150	$^\circ\text{C}$

### THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient <sup>a</sup>	$R_{thJA}$	100	$^\circ\text{C/W}$
--	------------	-----	--------------------

Note :

a. Surface Mounted on FR4 Board ,  $t \leq 10\text{sec}$  .

b. Pulse width limited by maximum junction temperature.

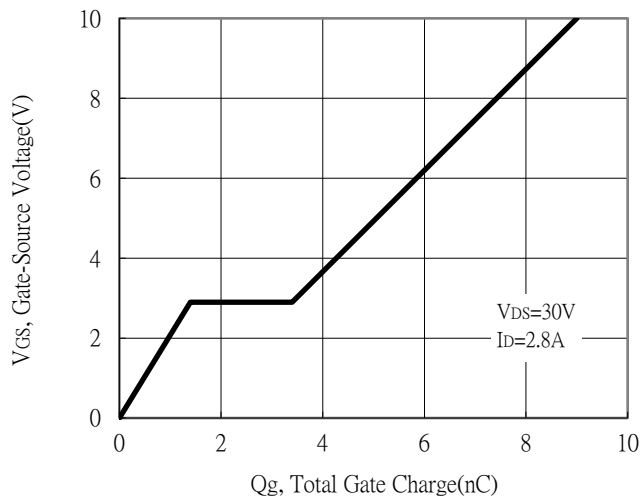
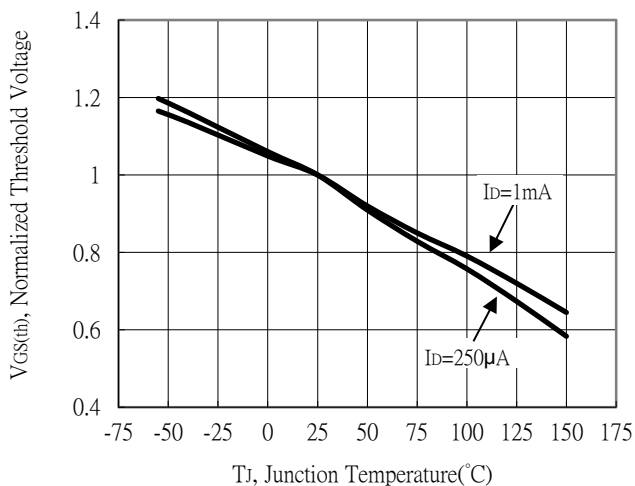
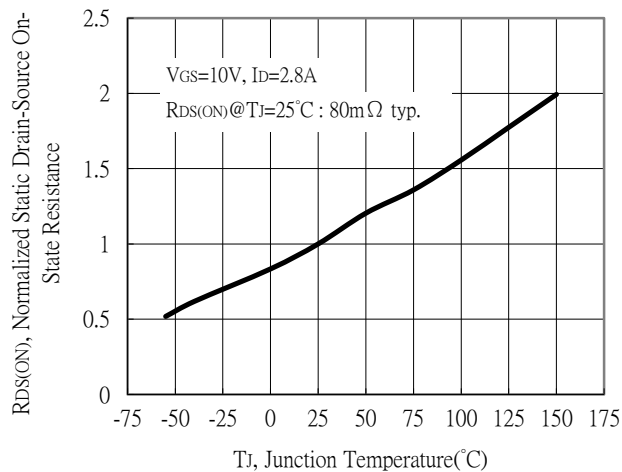
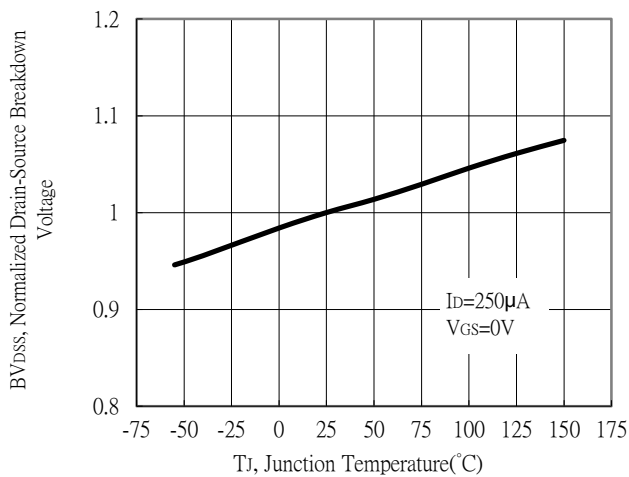
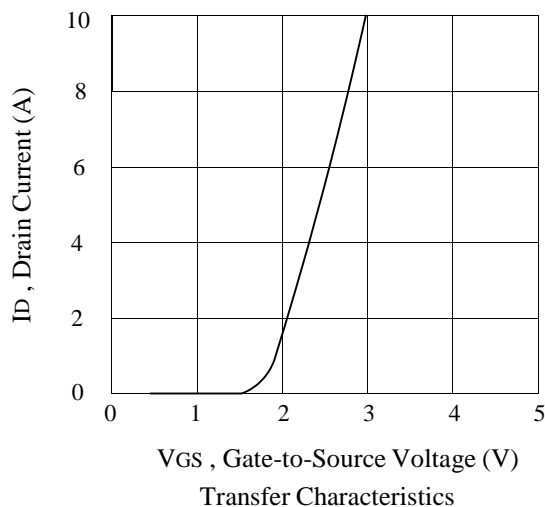
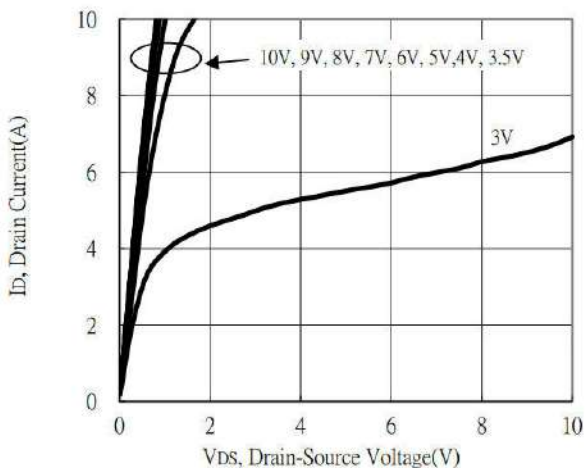
**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ <sup>c</sup>	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V , I <sub>D</sub> = 250uA	60			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 24V , V <sub>GS</sub> = 0V			1	uA
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V , V <sub>DS</sub> = 0V			±100	nA
<b>ON CHARACTERISTICS<sup>b</sup></b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250uA	1	1.5	2.5	V
Drain-Source On-State Resistance	R <sub>DSON</sub>	V <sub>GS</sub> = 10V , I <sub>D</sub> = 2.8A		80	95	m Ω
		V <sub>GS</sub> = 5V , I <sub>D</sub> = 2.3A		90	115	
		V <sub>GS</sub> = 4.5V , I <sub>D</sub> = 2.1A		95	120	
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> = 5V , I <sub>D</sub> = 2.8A		4		S
<b>DRAIN-SOURCE DIODE CHARACTERISTICS<sup>b</sup></b>						
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V , I <sub>S</sub> = 1.0A			1.2	V
<b>DYNAMIC CHARACTERISTICS<sup>c</sup></b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 15V , V <sub>GS</sub> = 0V f = 1.0MHz		386		pF
Output Capacitance	C <sub>OSS</sub>			27		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>			21		pF
<b>SWITCHING CHARACTERISTICS<sup>c</sup></b>						
Turn-On Delay Time	t <sub>D(ON)</sub>	V <sub>DD</sub> = 15V , I <sub>D</sub> = 1A V <sub>GEN</sub> = 10V R <sub>L</sub> = 15 Ω R <sub>GEN</sub> = 6 Ω		48		ns
Rise Time	t <sub>r</sub>			6.5		ns
Turn-Off Delay Time	t <sub>D(OFF)</sub>			22		ns
Fall Time	t <sub>f</sub>			4.1		ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = 15V I <sub>D</sub> = 3A V <sub>GS</sub> = 10V		9.2		nC
Gate-Source Charge	Q <sub>gs</sub>			1.5		nC
Gate-Drain Charge	Q <sub>gd</sub>			2		nC

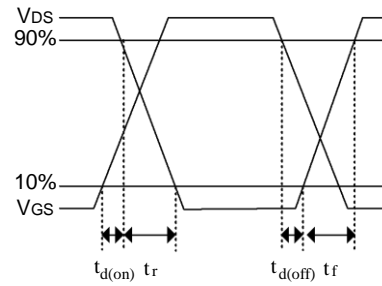
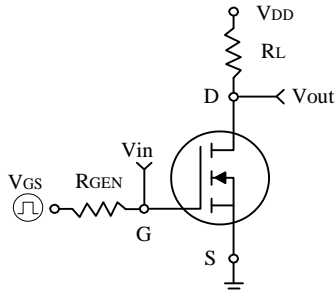
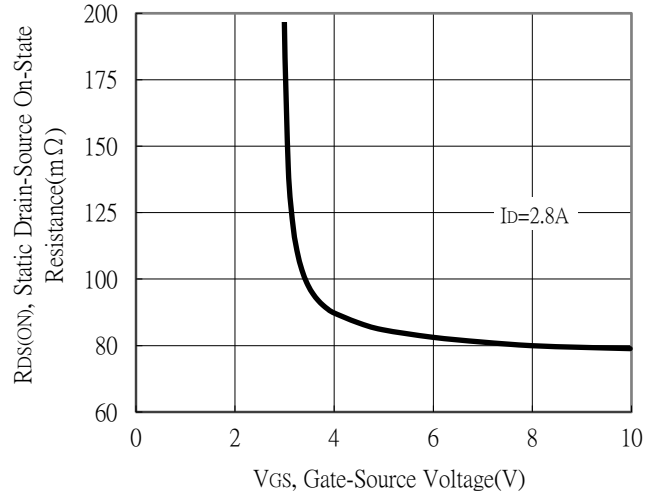
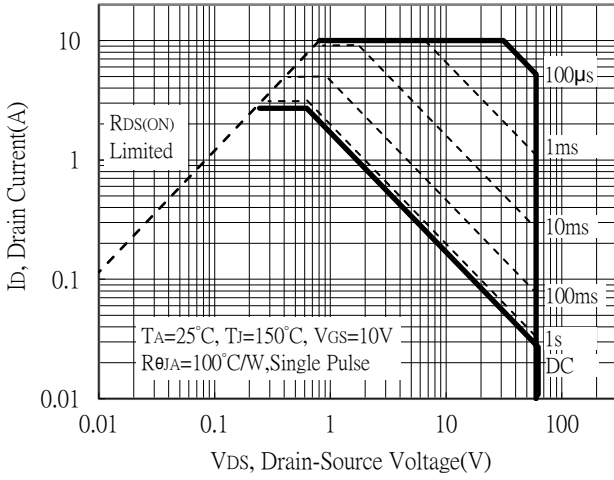
Note :

b. Pulse Test : Pulse width ≤ 300us , Duty Cycle ≤ 2% .

c. Guaranteed by design , not subject to production testing .



Maximum Safe Operating Area



Switching Test Circuit and Switching Waveforms

